

**Product / Package Information**

Package	SOIC_W
Body Size	300 mils
Lead Count	16
Terminal Finish	NiPdAu
MS Number	MS012946A

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes
Last Updated	4/29/2019

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	3.48 E-01	93.70	937000	64.49		644854
Thermosets	Epoxy Resin	Proprietary	1.11 E-02	3.00	30000	2.06		20646
Thermosets	Phenol Resin	Proprietary	1.11 E-02	3.00	30000	2.06		20646
Other inorganic materials	Carbon Black	1333-86-4	1.11 E-03	0.30	3000	0.21		2065
Subtotal			3.71 E-01	100.00	1000000	68.82		688211

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.45 E-01	97.57	975706	26.91		269136
Copper & its alloys	Iron	7439-89-6	3.39 E-03	2.28	22789	0.63		6286
Copper & its alloys	Zinc	7440-66-6	1.88 E-04	0.13	1263	0.03		348
Copper & its alloys	Phosphorus	7723-14-0	3.60 E-05	0.02	242	0.01		67
Subtotal			1.49 E-01	100.00	1000000	27.58		275837

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Nickel & its alloys	Nickel	7440-02-0	5.25 E-03	95.0	950000	0.97		9747
Precious Metals	Palladium	7440-05-3	2.27 E-04	4.1	41000	0.04		421
Precious Metals	Gold	7440-57-5	4.98 E-05	0.9	9000	0.01		92
Subtotal			5.53 E-03	100.0	1000000	1.03		10260

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious Metals	Gold	7440-57-5	1.19 E-03	99.00	990000	0.22		2204
Precious metals	Palladium	7440-05-3	1.20 E-05	1.00	10000	0.00		22
Subtotal			1.20 E-03	100.00	1000000	0.22		2226

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	1.03 E-02	100.0	1000000	1.91		19106

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.81 E-03	77.00	770000	0.34		3357
Other organic materials	Acrylic resin	Proprietary	1.65 E-04	7.00	70000	0.03		305
Other organic materials	Acrylate	Proprietary	1.29 E-04	5.50	55000	0.02		240
Other organic materials	Polybutadiene derivative	Proprietary	1.06 E-04	4.50	45000	0.02		196
Other organic materials	Epoxy resin	Proprietary	5.88 E-05	2.50	25000	0.01		109
Other organic materials	Butadiene Copolymer	Proprietary	3.53 E-05	1.50	15000	0.01		65
Others	Additive	Proprietary	3.53 E-05	1.50	15000	0.01		65
Others	Peroxide	Proprietary	1.18 E-05	0.50	5000	0.002		22
Subtotal			2.35 E-03	100.00	1000000	0.44		4359

<b>Package Totals</b>			<b>Weight (g)</b> 5.39 E-01			<b>Percentage (%)</b> 100.00		<b>PPM</b> 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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